

Approved Product

Product Features

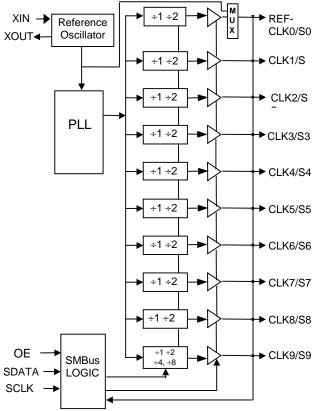
- Produces PCI output clocks that are individually selectable for 33.3 or 66.6 MHz under SMBus or strapping control.
- Separate output buffer power supply for reduced noise, crosstalk and jitter.
- input clock frequency standard 14.31818 MHz
- Output clocks frequency individually selectable via SMBus or hardware bi-directional pin strapping.
- SSCG EMI reduction at 1.0% width
- Individual clock disables via SMBus control
- All output clocks skewed within a 500 pS window
- Cycle to Cycle jitter ± 250 pS
- Output duty cycle is automatically 50% (±10%) adjusted
- Clock feed through mode and OE pins for logic testing
- Glitchless clock enabling and disabling transitions
- 28-pin TSSOP or SSOP package

Output Enable Logic Functionality Table

OE	CLK(0:9)	PLL
1 (HIGH)	Enabled	Running
0 (LOW)	Tri State	Stopped*

^{*}See Output Enable Control section of this datasheet.

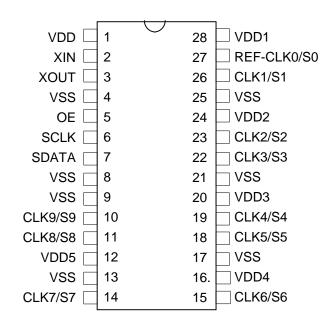
Block Diagram



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Pin Configuration



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Pin Description

Pin Description Pin Number	Pin Name	PWR	I/O	Description			
2	XIN	VDDA	I	This pin is the connection point for the devices Loop reference frequency. This may be either a CMOS 3.3 volt reference clock or the output of an external crystal. A nominal 14.31818 MHz frequency must be supplied to obtain the frequencies listed on this data sheet			
3	XOUT	VDDA	0	This pin the devices output drive that is to be used wher an external crystal is used. In this configuration the devi provides the analog gain function of a crystal oscillator. When the device is being supplied with an external reference frequency, this pin is left disconnected.			
1	VDDA	-	PWR	This pin is the power supply source for the internal PLL circuitry and core control logic. It should be bypassed separately from all other device VDD supply pins.			
5	OE	-	I	Output Enable. See logic table on page 1 for functionality			
12, 16, 20, 24, 28	VDD	-	PWR	Logic power for All buffers			
6	SDATA	VDDA	I/O	SMBus Serial data pin			
7	SCLK	VDDA	0	SMBus serial interface clock pin			
27	REF- CLK0/S0	VDD1	0				
26	CLK1/S1	VDD1	0				
23	CLK2/S2	VDD2	0				
22	CLK3/S3	VDD2	0	Individual output clocks and power up divisor select pins.			
19	CLK4/S4	VDD3	0	Each of these pins is both a clock output pin and, at			
18	CLK5/S5	VDD3	0	power up, a temporary input pin. When they act as an			
15	CLK6/S6	VDD4	0	input pin they set the initial output frequency of the device to either the input frequency or half of the input frequency.			
14	CLK7/S7	VDD4	0	Subsequently, the divisor may be changed or disabled via			
11	CLK8/S8	VDD5	0	the device's SMBus register bits. Reference clock and its			
10	CLK9/S9	VDD5	0	programmable input value is saved internally for when it PCI clock function is selected.			
4, 8, 9, 13, 17, 21, 25	VSS	-	PWR	Ground pins for the chip.			
1	VDD	-	PWR	Power for core logic			
28	VDD1	-	PWR	Power for CLK1 and CLK2 output buffers			
24	VDD2	-	PWR	Power for CLK3 and CLK4 output buffers			
20	VDD3	-	PWR	Power for CLK5 and CLK6 output buffers			
16	VDD4	-	PWR	Power for CLK7 and CLK8 output buffers			
12	VDD5	-	PWR	Power for CLK9 and CLK10 output buffers			

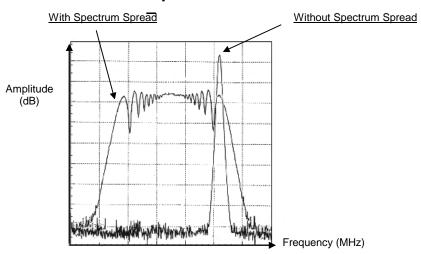
A bypass capacitor (0.1 mF) should be placed as close as possible to each Vdd pin.



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Spectrum Spread Clocking

Down Spread



Spectrum Analysis

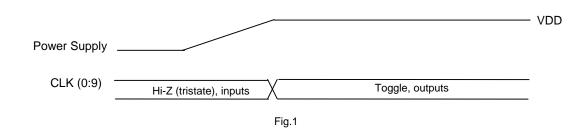
Spectrum Spreading Selection Table

Unspread Frequency in MHz	Down Spreading						
Frequency in winz							
	F Min	F Center	F Max	Spread			
Desired (actual)	(MHz)	(MHz)	(MHz)	(%)			
33.3 (xx.x)	33.00	33.16	33.3	+0 -1.00%			
66.6 (xx.x)	66.00	66.33	66.6	+0 -1.00%			



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Power Up Bi-Directional Pin Timing (all clock outputs)



Note: a pull-up or logic high programming voltage will select a 66.6 MHz output clock frequency on that specific pin. A logic low level will select a 33.3 MHz clock frequency in that specific pin.

Output Frequency Selections

The device contains 3 specific output mode type pins. They are:

REF-CLK0/S0

This pin powers up as a 33.3 or 66.6 MHz PCI clock. Via SMBus command byte 1 bit 4 it may be changed to be a 14.318 MHz clock. When it is acting as a PCI clock its frequency may be changed between 33 and 66 Mhz using SMBus command byte 1 bit 3. The PCI clock may also be initially set at device power up using the bi-directional programming capability of the pin (device pin number 27)

CLK (1:8)

These are dual frequency PCI clock pins that may be stopped enabled and have their frequency changed at power up and then on the fly (at any time) via their respective SMBus register control bits.

CLK9/S9

This bit acts in the same manner as the CLK (1:8) bits. Additionally by selection in SMBus byte 3 Bits 5 and 6 it can output both 16.5 Mhz or 8.25 Mhz on its pin. Like the other clock pins SMBus byte 3 Bit 6 is initially set (via the clocks bidirectional; pin function) at power up depending on the level of the clocks pin.

NOTE: Clocks REF-CLK0/S0 (pin 27) and CLK1/S1 (pin 26) are powered from VDD1 (pin 28). This data sheet characterizes the guaranteed performance of these 2 clocks with respect to jitter and skew. Designers that use this device need to understand that if these 2 clocks are operated at different frequencies (e.g., pin 27 is set to the REF output mode while pin 26 is enabled at either 33 pr 66 Mhz frequency mode) that the data sheet values of these clocks will not be guaranteed. It is therefor prudent to disable the CLK1 output when the REF-CLK0/S0 output has been programmed to output a 14.31818 Mhz clock to realize the devices best performance.



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Output Enable Control

The Output Enable Pin (pin 5) on this device serves two (2) purposes. The primary function is to force all clock outputs to a tri-state electrical mode. This is done to support automated testing of fabricated PCB assemblies.

The second function of this pin is to bring the internal circuitry of the device to a lower power mode when the pin is driven to a logic low level. In this mode, all unneeded circuitry (e.g., the PLL, counters and clock control logic) have their power removed. Designers who use this functionality should pay close attention to the T_{OEL} characteristic listed in the AC Parameters section of this datasheet. This function is particularly useful in mobil designs where power savings is a crucial design factor. Data stored in the SMBus registers is maintained during OE active periods.

Application Note for Selection on BI-DIRECTIONAL Pins

Pins 10, 11, 14, 15, 18, 19, 22, 23, 26 and 27 are Power up bi-directional pins and are used for selecting power up output frequencies of this devices output clocks (see Pin description, Page 2). During power-up of the device, these pins are in input mode, therefore, they are considered input select pins internal to the IC, these pins have a large value pull-up each (250K Ω), therefore, a selection "1" is the default and will select a 66 MHz output frequency. If the system uses a slow power supply (over 5 ms settling time), then it is recommended to use an external pull-up (Rup) in order to insure a high selection. In this case, the designer may choose one of two configurations, see FIG. 3A and Fig. 3B.

Fig. 3A represents an additional pull up resistor $50K\Omega$ connected from the pin to the power line, which allows a faster pull to a high level.

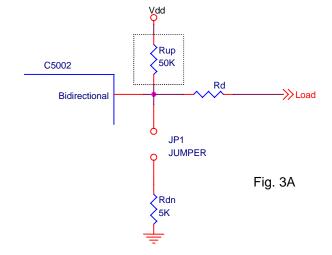
If a selection "0" is desired, then a jumper is placed on JP1 to a $5K\Omega$ resistor as implemented as shown in Fig. 3A. Please note the selection resistors (Rup and Rdn) are placed before the Damping resistor (Rd) close to the pin.

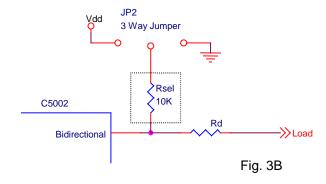
Fig. 3B represents a single resistor $10K\Omega$ connected to a 3-way jumper, JP2. When a "1" selection is desired, a jumper is placed between leads 1 and 3. When a "0" selection is desired, a jumper is placed between leads 1 and 2.

If the system power supply is fast (less than 5 mSec settling time), then FIG 3A only applies and Pull up Rup resistor is not necessary.

The electrical length of the trace that connects the selection resistor to the devices pin should be kept as short as possible.

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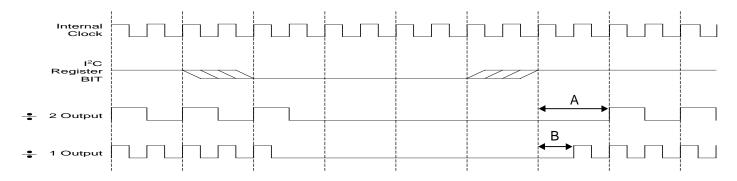
Input and Output Relationships

The device acts a PCI clock generator. Output clocks may be individually controlled to be either 33.3 or 66.6 MHz in frequency by setting or clearing the clocks respective SMBus control register bit. All output clocks are rising edge aligned to within a shared 500 pS window. There is no specified relationship between the input reference clock and the output clocks.

Clock Enable Functions and Timing

Each output clock may be either disabled or enabled by either setting or clearing its respective SMBus register control bit.

All clocks are stopped in the low state. All clocks maintain a valid high period before transitioning from running to stopped. The clocks transition between running and stopped occurs immediately after the SMBus register bit is cleared and the clock transitions to a low state. See figure below.



A: represents one output ÷2 clock cycle (one 33.3 MHZ cycle period).

B: represents one output clock ÷ 1 cycle (one 66.6 MHZ cycle period).

Output Frequency Change Relationships

The SMBus registers are initially set (initialized) by the voltage levels present on the clocks output pins at power up. Subsequently these bits may be changed via SMBus commands.

Output clocks have the capability to be changed, on the fly, via the devices SMBus register bits. If Synchronous switching is required, it may be achieved by first disabling a specific clock, changing its frequency and then re-enabling it via the SMBus register control bits that are provided for these functions.

Synchronous switching is defines at the changing of the output frequency of a clock from one frequency to another in such a manner as to not produce any clock cycles shorter than the higher of the 2 frequencies or longer than the period of the lower of the 2 frequencies. The disable and enable SMBus register bit control of each clock is logically implemented to eliminate clock glitches when each clock is either enabled or enabled.



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CAUTION: Switching clock frequencies without first disabling the clock may produce an output clock glitch (short or stretched period clock) during frequency transition!)

2-Wire SMBus Control Interface

The 2-wire control interface implements write block mode write only slave interface. Sub addressing is not supported, thus all <u>preceding bytes must be sent</u> in order to read or change one of the control bytes. The 2-wire control interface allows each clock output to be individually controlled.

During normal data transfer, the SDATA signal only changes when the SDCLK signal is low, and is stable when SDCLK is high. There are two exceptions to this. A high to low transition on SDATA while SDCLK is high is used to indicate the start of a data transfer cycle. A low to high transition on SDATA while SDCLK is high indicates the end of a data transfer cycle. Data is always sent as complete 8-bit bytes, after which an acknowledge is generated. The first byte of a transfer cycle is a 7-bit address with a Read/Write bit as the LSB (bit 0). Data is transferred MSB (bit 7) first.

The device will respond to writes up to 6 bytes (max) of data to address **<u>D0</u>**. The device will not respond to any other control interface conditions.

Serial Control Registers

NOTE: The Pin# column lists the affected pin number where applicable. The @Pup column gives the state at true power up. Bytes are set to the values shown only on true power up.

Following the acknowledge of the Address Byte (D0), two additional bytes must be sent:

- 1) "Command Code " byte, and
- 2) "Byte Count" byte.

Although the data (bits) in these two bytes are considered "don't care"; they must be sent and will be acknowledged.

After the Command Code and the Count bytes have been acknowledged, the described sequence below (Byte 0, Byte 1, Byte2,) will be valid and acknowledged.

Byte 0: Function Select Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description
7	1	14	CLK7 (Active = 1, Forced low = 0)
6	1	15	CLK6 (Active = 1, Forced low = 0)
5	1	18	CLK5 (Active = 1, Forced low = 0)
4	1	19	CLK4 (Active = 1, Forced low = 0)
3	1	22	CLK3 (Active = 1, Forced low = 0)
2	1	23	CLK2 (Active = 1, Forced low = 0)
1	1	26	CLK1 (Active = 1, Forced low = 0)
0	1	27	CLK0 (Active = 1, Forced low = 0)



Serial Control Registers (Cont.)

Byte 1: Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description					
7	1	-	0= Test Mode (XIN replaces VCO output), 1=Normal					
6	0	10	Bit 6 Bit 5 PCI9 Frequency					
5	HW	10	0 0 33 MHz					
			0 1 66 Mhz					
			1 0 16.5 Mhz					
			1 1 8.25 MHz					
4	0	27	REF-CLK0 mode (1 = REF, 0 = PCI0)					
3	HW	27	CLK0 (33.3 MHz = 0, 66.6 MHz = 1)(if Byte 3 Bit 4=0)					
2	0	-	SSCG (OFF = 0, ON = 1)					
1	1	10	CLK9 (Active = 1, Forced low = 0)					
0	1	11	CLK8 (Active = 1, Forced low = 0)					

Byte 2: Clock Register (1 = 66.6 MHz, 0 = 33.3 MHz)

Bit	@Pup	Pin#	Description
7	HW	11	CLK8 (33.3 MHz = 0, 66.6 MHz = 1)
6	HW	14	CLK7 (33.3 MHz = 0, 66.6 MHz = 1)
5	HW	15	CLK6 (33.3 MHz = 0, 66.6 MHz = 1)
4	HW	18	CLK5 (33.3 MHz = 0, 66.6 MHz = 1)
3	HW	19	CLK4 (33.3 MHz = 0, 66.6 MHz = 1)
2	HW	22	CLK3 (33.3 MHz = 0, 66.6 MHz = 1)
1	HW	23	CLK2 (33.3 MHz = 0, 66.6 MHz = 1)
0	HW	26	CLK1 (33.3 MHz = 0, 66.6 MHz = 1)

Note: HW = Power up programmed via hardware (voltage at pin).



Maximum Ratings

Voltage Relative to VSS:

Voltage Relative to VDD:

Storage Temperature:

O°C to + 125°C

Operating Temperature:

Maximum Power Supply:

7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range:

VSS<(Vin or Vout)<VDD
Unused inputs must always be tied to an appropriate

logic voltage level (either VSS or VDD).

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DC Parameters

Characteristic	Symbol	Min	Тур	Max	Units	Conditions
VDD supply		3.0	-	3.6	Vdc	
Temperature		0		70	°C	
Input Low Voltage	VIL	-	-	0.8	Vdc	-
Input High Voltage	VIH	2.0	-	-	Vdc	-
Input Low Current	IIL			-100	μA	
Input High Current	IIH			100	μA	
Tri-State leakage Current	loz	-	-	10	μA	
Dynamic Supply Current	Idd	-	-	150	mA	All outputs fully loaded at 30 pF at 66 MHz
Static Supply Current		-	-	35	MA	All outputs driven load with SMBus control – 66 MHz



AC Parameters

Characteristic	Symbol	Min	Тур	Max	Units	Conditions			
Input (REF) Duty Cycle	-	40	50	60	%	When external reference is used			
REF input frequency	FREF	12	14.3	16	MHz				
Output Duty Cycle	-	45	50	55	%	Measured at 1.5V			
Skew from any output to any	tOFF _{CC}	0	200	500	pS	30 pF Load, Measured at 1.5V			
output						(all outputs fall within a 500 pSec time window)			
Jitter Cycle to Cycle	tJ _{pp}	-250	-	+250	pS	Any Output			
Output Freq.	Fo	30	33/66	70	MHz	At device output pins			
Long term output jitter	tJ _{lt}	-500	-	+500	pS	Any output, 2 minute sample			
Power up to output lock time	$T_{\nablaR}T_L$	-	-	10	mS	Measured from the point VDD reaches 3.15 Volts with a stable reference			
OE Rising to Output Lock time	T _{OEL}	-	-	3	mS	Mesured in a stabilized environment where OE has been previously been brought to a logic low level.			
Input Capacitance CIN 4 pF (FBIN and REF pins)						(FBIN and REF pins)			
VDD = VDDA =3.3V ±5%, TA = 0°C to +70°C									

Buffer Characteristics (All Output Clocks))

Characteristic	Symbol	Min	Тур	Max	Units	Conditions		
Pull-Up Current	IOH _{min}	22	-	-	mA	Vout = VDD5V		
Pull-Up Current	IOH _{max}	-45	-	-	mA	Vout = 1.5V		
Pull-Down Current	IOL _{min}	26	-	-	mA	Vout = 0.4V		
Pull-Down Current	IOL _{max}	65	-	-	mA	Vout = 1.5V		
Rise Time Min Between 0.4 V and 2.4 V	TR _{min}	0.4	-	2.5	nS	30 pF Load		
VDD= VDDA = 3.3V ±5%, TA = 0°C to +70°C								



Crystal and Reference Oscillator Parameters

Characteristic	Symbol	Min	Тур	Max	Units	Conditions
Frequency	Fo	12.00	14.31818	16.00	MHz	
Tolerance	TC	-	-	+/-100	PPM	Calibration Note 1
	TS	-	-	+/- 100	PPM	Stability (Ta -10 to +60C) Note 1
	TA	-	-	5	PPM	Aging (first year @ 25C) Note 1
Mode	ОМ	-	-	-		Parallel Resonant
Pin Capacitance	СР		32		pF	Capacitance of XIN and Xout pins to ground (each)
DC Bias Voltage	V_{BIAS}	0.3Vdd	Vdd/2	0.7Vdd	V	
Startup time	Ts	-	-	30	μS	
Load Capacitance	CL	-	16	-	pF	See calculation section below
Effective Series resistance (ESR)	R1	-	-	40	Ohms	
Power Dissipation	DL	-	-	0.10	mW	Note 1
Shunt Capacitance	СО	-		8	pF	Crystal's internal package capacitance (total)

For maximum accuracy, the total circuit loading capacitance should be equal to CL. This loading capacitance is the effective capacitance across the crystal pins and includes the device pin capacitance (CP) in parallel with any circuit traces, the clock generator and any onboard discrete load capacitors.

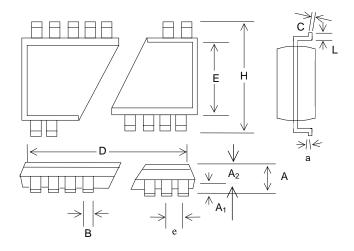
Budgeting Calculations

Typical trace capacitance, (< half inch) is 4 pF, Load to the crystal is therefore = 2.0 pF Clock generator internal pin capacitance of 32 pF, Load to the crystal is therefore = 16.0 pF The total capacitance see by the crystal would therefore be = 18.0 pF.

Note 1: It is recommended but not mandatory that a crystal meets these specifications.



Package Drawing and Dimensions

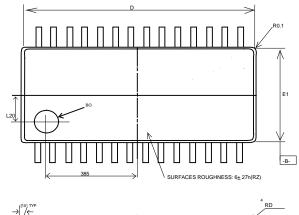


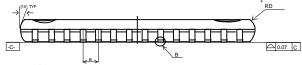
28 Pin SSOP Outline Dimensions

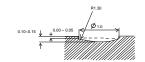
		INCHES		MILLIMETERS			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.068	0.073	0.078	1.73	1.86	1.99	
A ₁	0.002	0.005	0.008	0.05	0.13	0.21	
A2	0.066	0.068	0.070	1.68	1.73	1.78	
В	0.010	0.012	0.015	0.25	0.30	0.38	
С	0.005	0.006	0.009	0.13	0.15	0.22	
D	0.397	0.402	0.407	10.07	10.20	10.33	
E	0.205	0.209	0.212	5.20	5.30	5.38	
е	0.	0256 BSC	;	0.65 BSC			
Н	0.301`	0.307	0.311	7.65	7.80	7.90	
а	0°	4°	8°	0°	4°	8°	
L	0.022	0.030	0.037	0.55	0.75	0.95	



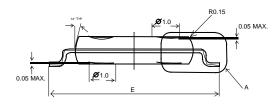
Package Drawing and Dimensions (Cont.)

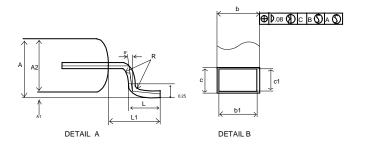






SECTION V-V





28 Pin TSSOP Dimensions

		INCHES	MILLIMETERS			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
Α	-	-	0.047	-	-	1.20
A1	0.002	0.004	0.006	0.05	0.10	0.15
A2	0.037	0.039	0.041	0.95	1.00	1.05
L	0.019	0.023	0.029	0.50	0.60	0.75
L1	0.035	0.039	0.043	0.90	1.00	1.10
b	0.007	-	0.011	0.19	-	0.30
b1	0.007	0.008	0.010	0.19	0.22	0.25
С	0.004	-	0.007	0.105	-	0.175
c1	0.004	0.005	0.006	0.105	0.125	0.145
θ	0°	-	8°	0°	-	8°
е		0.026 BS0	5	0.65 BSC		
D	0.378	0.382	0.386	9.6	9.7	9.8
Е	0.244	0.252	0.260	6.2	6.4	6.6
E1	0.169	0.173	0.177	4.3	4.4	4.5
R	0.035	-	-	0.9	-	-



Ordering Information

Part Number	Package Type	Production Flow
C5002BTB	28 PIN TSSOP	Commercial, 0°C to +70°C
C5002BYB	28 PIN SSOP	Commercial, 0°C to +70°C

Note: The ordering part number is formed by a combination of device number, device revision, package style, and

screening as shown below.

Marking: Example: Cypress

C5002BYB

Date Code, Lot #

C5002 B Y B

Flow

B = Commercial, 0°C to + 70°C

Package Y = SSOP

T = TSSOP

Revision

Device Number





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Document Title: C5002 Low Skew Miltiple Frequency PCI Clock Generator with EMI

Reducing SSCG

Document Number: 38-07014

REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	109129	08/29/01	NDP	Convert from IMI to Cypress